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NAME OF INVENTOR(S): Yoshino	
RECEIPT DATE & SERIAL NO.: <b>Serial No.: 10/621,771</b>	
TITLE OF INVENTION: SEMICONDUCTOR PACKAGE INSULATION FILM AND MANUFACTURING METHOD THEREOF	
Filing Date: 7/17/2003	
TI FILE NO.: <b>TI-29448.1</b>	DEPOSIT ACCT. NO.: <b>20-0668</b>
FAXED: <u>11-29-04</u> DUE: 11/12/2004 ATTY/SECY: WDS/tc	

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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Yoshino  
Serial No: 10/621,771  
Filed: 7/17/2003  
For: SEMICONDUCTOR PACKAGE INSULATION FILM AND  
MANUFACTURING METHOD THEREOF

Docket No: TI-29448.1  
Examiner: Clark, Sheila V.  
Art Unit: 2815

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**AMENDMENT UNDER 37 C.F.R. § 1.115**

Assistant Commissioner For Patents  
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Dear Sir:

Responsive to the Office Action mailed August 12, 2004 in connection with the above identified application, Applicants respectfully submit the following amendments and remarks.

TI-29448.1 - 1 -